

NOTES:

1.0. MATERIALS :

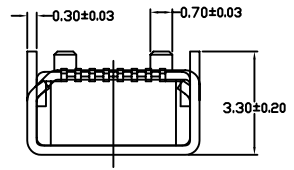
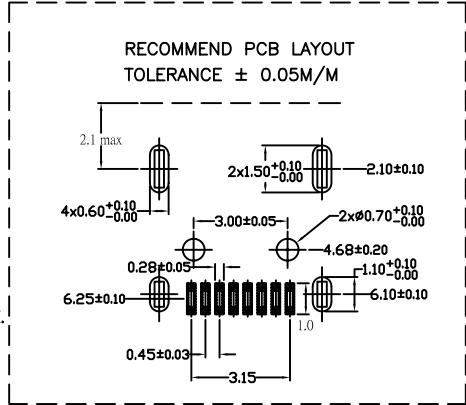
- 1.1. ALL DIMENSIONS ARE IN M/M.
- 1.2. SHELL MATERIAL : COPPER ALLEY 0.30±0.02.
FINISH : GOLD PLATED OVER Ni , UNDERPLATED.
- 1.3. INSULATOR MATERIAL : HI-TEMPERATURE , LCP THERMOPLASTIC UL 94V-0
- 1.4. CONTACT AREA : 10u" Au OVER 30u" Ni UNDERPLATED.
GOLD FLASH THE BACK SOLDER TAIL .

2.0. RATING :

- 2.1. VOLTAGE : 30 VAC (R.M.S).
- 2.2. CURRENT : 1.0 AMPERE MAXIMUM PER CONTACT AT 30° C T-RISE.
- 2.3. TEMPERATURE : -55°C TO +85°C.

3.0. ELECTRICAL SPECIFICATION :

- 3.1. CONTACT RESISTANCE : 30 MILLIOHMS MAXIMUM INITIAL.
- 3.2. INSULATION RESISTANCE : 1,000 MEGOHMS MINIMUM.
- 3.3. DIELECTRIC WITHSTANDING VOLTAGE : 750 VAC AT SEE LEVER.



ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
①	SHELL	1	COPPER ALLOY	FLASH GOLD PLATED
②	HOUSING	1	HI-TEMPERATURE THERMOPLASTIC UL 94V-0	MOLDED BLACK
③	CONTACT	8	COPPER ALLOY	CONTACT AREA: AU 10u" MIN PLATING SOLDER TAIL AREA: AU FLASH PLATING

Remove burrs, Break sharp edges 0.4 R. max.
Stamp part no. in area indicated by "x"
Unless otherwise specified
Angle: ±°

XX.X =±0.20 .X" =±
XX.XX =±0.10 .XX" =±
XX.XXX =±0.05 .XXX" =±.

01	設計發行	CHEN	05/05/2004	PART NO	YMUVG30312
TITLE		MIN-B SOCKET 8 PIN			
SHEET	1/1	App.	Date	Chk.	Date
SCALE	1:1	CHEN	05/05/2004	CHEN	05/05/2004